

*CLAIM AMENDMENTS*

Claims 1-13 (Canceled).

14. (New) A method of chemical mechanical polishing of an object comprising:  
supplying a slurry to a polishing apparatus including a polisher and the object to be polished;

measuring particle information, including at least one of dispersion of particles and distribution of particle sizes, of the slurry being supplied to the polishing apparatus; and  
controlling polishing speed, based on the particle information.

15. (New) The method according to claim 14 including controlling the polishing speed by adjusting a physical variable of the polisher.

16. (New) The method according to claim 15, wherein the physical variable is at least one of a rotation speed of the polisher, rotation speed of the object, and force applied by the polisher to the object.

17. (New) The method according to claim 14 including supplying a mixture of a first slurry and a second slurry to the polishing apparatus as the slurry.

18. (New) The method according to claim 17 including controlling mixing ratio between the first slurry and the second slurry on the particle information.

19. (New) The method according to claim 18, further comprising:  
detecting the polishing speed at which the object is polished; and  
controlling the mixing ratio based on the polishing speed.

20. (New) A method of chemical mechanical polishing of an object comprising:  
supplying a slurry to a polishing apparatus including a polisher and the object to be polished;

measuring particle information, including at least one of dispersion of particle and distribution of particle sizes, of the slurry being supplied to the polishing apparatus; and  
controlling polishing time, based on the particle information.